Korean International Semiconductor Conference & Exhibition
on Manufacturing Technology 2025

# KISM 2025 BUSAN

Re:Innovation of Semiconductor Manufacturing for AI Ecosystem

| [WeF3] Advanced Designs, Processing, and Reliability | |
|---|---|
| Session Date | November 12 (Wed.), 2025 |
| Session Time | 16:05-17:45 |
| Session Room | Room F (Panorama Room, 16F) |
| Session Chair | Dr. Tae-Ik Lee (KITECH, Korea) |

**[WeF3-1] [Invited]** **16:05-16:25**

**Advanced Flip-Chip Bonding Process via Intense Pulsed Light Irradiation: From Single-Chip to Multi-Chip Stacking Applications**

Young-Min Ju, Jong-Whi Park, Hyeong-bin Park, Yun-Joong Kim, and Hak-Sung Kim (Hanyang Univ., Korea)

**[WeF3-2] [Invited]** **16:25-16:45**

**Statistical Signal Integrity Analysis with Nonideal Buffer of DFE for Chiplet**

Junyong Park (Kyung Hee Univ., Korea)

**[WeF3-3] [Invited]** **16:45-17:05**

**Visualized Thermo-Mechanical Failure Mechanisms in Advanced Semiconductor Package Interconnects via Microscale Deformation Analysis**

Tae-Ik Lee (KITECH, Korea)

**[WeF3-4]** **17:05-17:25**

**3D-Printed Organic Interposer with Embedded Fan-Out Interconnects Enabled by Additive Manufacturing**

Haksoon Jung and Jimin Kwon (UNIST, Korea)

**[WeF3-5]** **17:25-17:45**

**Predictive Analysis of Signal Transmission in Pogo Pin–Load Board**

Jonghee Park and Youbean Kim (Myongji Univ., Korea)